

LINEAR TECHNOLOGY MATERIALS DECLARATION

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(Engineering Calculation)

DFN 2mm X 2mm Exp. Pad

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TOTAL MASS (g) : 0.009357

| COMPONENT MATERIAL  | VENDOR/INDUSTRY NAMES            | CONSTITUENT NAME          | CAS NUMBER | CONSTITUENT MASS (g) | CONSTITUENT (PPM) OF MATERIAL | CONSTITUENT (PPM) OF TOTAL PKG. |
|---------------------|----------------------------------|---------------------------|------------|----------------------|-------------------------------|---------------------------------|
| Active Device       | Linear Technology                | Silicon (Si)              | 7440-21-3  | 0.000453             | 1000000                       | 48411.2734375                   |
| Die Coat            | Dow Corning                      | Silicone                  | 69430-27-9 | 0.000000             | 0                             | 0                               |
| Lead Frame          | Cu                               | Copper (Cu)               | 7440-50-8  | 0.002935             | 975000                        | 313658.03125                    |
|                     |                                  | Iron (Fe)                 | 7439-89-6  | 0.000072             | 24000                         | 7694.50683594                   |
|                     |                                  | Phosphorus (P)            | 7723-14-0  | 0.000001             | 300                           | 106.868148804                   |
|                     |                                  | Zinc (Zn)                 | 7440-66-6  | 0.000002             | 700                           | 213.736297607                   |
|                     |                                  | Nickel (Ni)               | 7440-02-0  | 0.000000             | 0                             | 0                               |
|                     |                                  | Silicon (Si)              | 7440-21-3  | 0.000000             | 0                             | 0                               |
|                     |                                  | Magnesium (Mg)            | 7439-95-4  | 0.000000             | 0                             | 0                               |
|                     |                                  | Tin (Sn)                  | 7440-31-5  | 0.000000             | 0                             | 0                               |
|                     |                                  | Lead Frame Total:         |            | 0.003010             | 1000000                       | 321673.15625                    |
| Plating             | PMI                              | Exter. Plating Pb         | 7439-92-1  | 0.000000             | 0                             | 0                               |
|                     |                                  | Exter. Plating Sn         | 7440-31-5  | 0.000136             | 1000000                       | 14568.7792969                   |
|                     |                                  | External Plating Total:   |            | 0.000136             | 1000000                       | 14568.7792969                   |
|                     |                                  | Inter. Plating Ni         | 7440-02-0  | 0.000000             | 0                             | 0                               |
|                     |                                  | Inter. Plating Ag         | 7440-22-4  | 0.000072             | 1000000                       | 7694.50683594                   |
|                     |                                  | Internal Plating Total:   |            | 0.000072             | 1000000                       | 7694.50683594                   |
| Die Attach          | ELECTRICALLY CONDUCTIVE ADHESIVE | Silver (Ag)               | 7440-22-4  | 0.000345             | 750000                        | 36869.515625                    |
|                     |                                  | Tin (Sn)                  | 7440-31-5  | 0.000000             | 0                             | 0                               |
|                     |                                  | Lead (Pb)                 | 7439-92-1  | 0.000000             | 0                             | 0                               |
|                     |                                  | Silica (SiO2)             | 60676-86-0 | 0.000000             | 0                             | 0                               |
|                     |                                  | Indium (In)               | 7440-74-6  | 0.000000             | 0                             | 0                               |
|                     |                                  | Metal Oxide               |            | 0.000000             | 0                             | 0                               |
|                     |                                  | Antimony (Sb)             | 7440-36-0  | 0.000000             | 0                             | 0                               |
|                     |                                  | Resin (EP)                |            | 0.000115             | 250000                        | 12289.8378906                   |
|                     |                                  | Die Attach Total:         |            | 0.000460             | 1000000                       | 49159.3515625                   |
| Encapsulation       | MULTI-AROMATIC RESIN Br/Sb FREE  | Resin (EP)                |            | 0.000677             | 130000                        | 72349.734375                    |
|                     |                                  | Bromine (Br)              | 40039-93-8 | 0.000000             | 0                             | 0                               |
|                     |                                  | Silica (SiO2)             | 60676-86-0 | 0.004481             | 860000                        | 478876.1875                     |
|                     |                                  | Antimony Trioxide (Sb2O3) | 1309-64-4  | 0.000000             | 0                             | 0                               |
|                     |                                  | Metal Hydroxide           |            | 0.000000             | 0                             | 0                               |
|                     |                                  | Carbon Black (C)          | 1333-86-4  | 0.000052             | 10000                         | 5557.14355469                   |
|                     |                                  | Encapsulation Total:      |            | 0.005210             | 1000000                       | 556783.0625                     |
| Bond Wire Estimated | AFW/TANAKA/ Kn                   | Gold (Au)                 | 7440-57-5  | 0.000016             | 1000000                       | 1709.89038086                   |
|                     |                                  |                           |            |                      | TOTAL MASS (g) :              | 0.009357                        |